

<b>PATENT ASSIGNMENT COVER SHEET</b>
--------------------------------------

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3001480

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	PARTIAL ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KYOTO UNIVERSITY	08/08/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KYOTO UNIVERSITY
<b>Street Address:</b>	36-1, YOSHIDA-HONMACHI
<b>Internal Address:</b>	SAKYO-KU, KYOTO-SHI
<b>City:</b>	KYOTO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	6068501
<b>Name:</b>	NIPPON PAPER INDUSTRIES CO., LTD.
<b>Street Address:</b>	4-1, OJI 1-CHOME, KITA-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1140002
<b>Name:</b>	DIC CORPORATION
<b>Street Address:</b>	35-58, SAKASHITA 3-CHOME, ITABASHI-KU
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	1748520
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12737562
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(866)658-1050
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	(202) 478-7375
<b>Email:</b>	jarmstrong@edwardswildman.com
<b>Correspondent Name:</b>	EDWARDS WILDMAN PALMER LLP
<b>Address Line 1:</b>	P.O. BOX 55874
<b>Address Line 4:</b>	BOSTON, MASSACHUSETTS 02205

PATENT

<b>ATTORNEY DOCKET NUMBER:</b>	87846(302610)
<b>NAME OF SUBMITTER:</b>	JAMES E. ARMSTRONG, IV
<b>SIGNATURE:</b>	/James E. Armstrong, IV/
<b>DATE SIGNED:</b>	08/28/2014
<b>Total Attachments: 3</b> source=Assignment of Partial Rights#page1.tif source=Assignment of Partial Rights#page2.tif source=Assignment of Partial Rights#page3.tif	

## ASSIGNMENT

WHEREAS, KYOTO UNIVERSITY, a university organized under and pursuant to the laws of Japan having its principal place of business at 36-1, Yoshidahonmachi, Sakyo-ku, Kyoto-shi, Kyoto 6068501, Japan (hereinafter referred to as Assignor), is the sole and exclusive owner, by assignment, of the Patent Application listed in Schedule A; and

### WHEREAS,

- NIPPON PAPER INDUSTRIES CO., LTD., a company organized under and pursuant to the laws of Japan, having its principal place of business at 4-1, Oji 1-chome, Kita-ku, Tokyo 1140002, Japan; and
- DIC CORPORATION, a corporation organized under and pursuant to the laws of Japan, having its principal place of business at 35-58, Sakashita 3-chome, Itabashi-ku, Tokyo 1748520, Japan,

(hereinafter referred to as Assignees), are desirous of acquiring a partial right, title and interest in, to and under said Patent Application and the invention covered thereby;

NOW, THEREFORE, in consideration of and in exchange for the sum of One Dollar (\$1.00) and other good and valuable consideration, receipt of which is hereby acknowledged, the said Assignor has sold, assigned, transferred and set over, and does hereby sell, assign, transfer and set over to the said Assignees, a partial undivided right, title and interest for the United States of America and all other countries in and to said applications for all original, divisional, continuation, continuation-in-part, substitute or reissue applications and patents applied for or granted therefore in the United States of America and all other countries on the attached list of *Schedule A*. Assignor hereby retains a partial undivided right, title and interest for the United States of America and all other countries in and to said applications for all original, divisional, continuation, continuation-in-part, substitute or reissue applications and patents applied for or granted therefore in the United States of America and all other countries on the attached list of *Schedule A*. The Commissioner of Patents and Trademarks is hereby authorized and requested to issue all patents on *Schedule A* to all assignees herein, as assignees of the partial, undivided interest

87848(302810)

1

AM 33731536.1

PATENT  
REEL: 033647 FRAME: 0624

therein; and the undersigned for itself and its legal representatives, heirs and assigns does hereby agree and covenant without further remuneration, to execute and deliver all divisional, continuation, continuation-in-part, reissue and other applications for Letters Patent and all assignments thereof to said assignees or their assigns, to communicate to said assignees or their representatives all facts known to the undersigned respecting said invention listed on *Schedule A* whenever requested, to testify in any interferences or other legal proceedings in which said applications or patents may become involved, to sign all lawful papers, make all rightful oaths, and do generally everything necessary to aid assignee, its successors, assigns and nominees to obtain patent protection for said inventions listed on *Schedule A* in the United States of America and all other countries, the expenses incident to said application listed on *Schedule A* to be borne and paid by said assignees.

Now, therefore, upon execution of this assignment, the assignees of the entire undivided right, title and interest will be:

1. Nippon Paper Industries, Co., Ltd.;
2. DIC Corporation; and
3. Kyoto University.

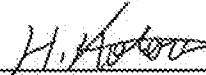
87848(302810)

**SCHEDULE A**

<b>Application Number</b>	<b>Filing Date</b>	<b>Inventor</b>	<b>Title</b>	<b>Ctry</b>
12/737,562	Jan 26, 2011	Hiroyuki Yano, et al.	MOLDING MATERIAL CONTAINING UNSATURATED POLYESTER RESIN AND MICROFIBRILLATED PLANT FIBER	US

Date: August 8, 2014

Signature: \_\_\_\_\_

  
Authorized signatory for Kyoto University  
Hidetoshi KOTERA,  
Director of Office of Society-Academia  
Collaboration for Innovation

87948(302810)